

Application No.: 10/055,499

Docket No.: JCLA8534-R

**In The Claims:**

**Claims 1-280. (canceled)**

281. (new) A method for fabricating an electronic component, comprising:  
joining a die and a substrate, wherein said die has a top surface at a horizontal level; and  
after said joining said die and said substrate, depositing a bump over said horizontal level,  
wherein said bump comprises gold.

282. (new) A method for fabricating an electronic component, comprising:  
providing a die having a top surface at a horizontal level;  
depositing an insulation layer over said horizontal level, wherein said insulation layer  
comprises a porous structure; and  
depositing a metal layer over said horizontal level.

283. (new) A method for fabricating an electronic component, comprising:  
providing a die having a top surface at a horizontal level;  
depositing a metal layer over said top surface and extending to a place not over said die;  
and  
depositing a passive device over said horizontal level.

284. (new) A method for fabricating an electronic component, comprising:  
providing a die having a top surface at a horizontal level; and

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depositing a waveguide over said horizontal level.

285. (new) A method for fabricating an electronic component, comprising:

providing a die having a top surface at a horizontal level; and

depositing a micro electronic mechanical sensor (MEMS) over said horizontal level.

286. (new) A method for fabricating an electronic component, comprising:

providing a substrate comprising an organic material;

joining multiple dies with said substrate;

depositing a metal layer over said multiple dies, wherein said depositing said metal layer  
comprises electroplating; and

cutting said substrate.